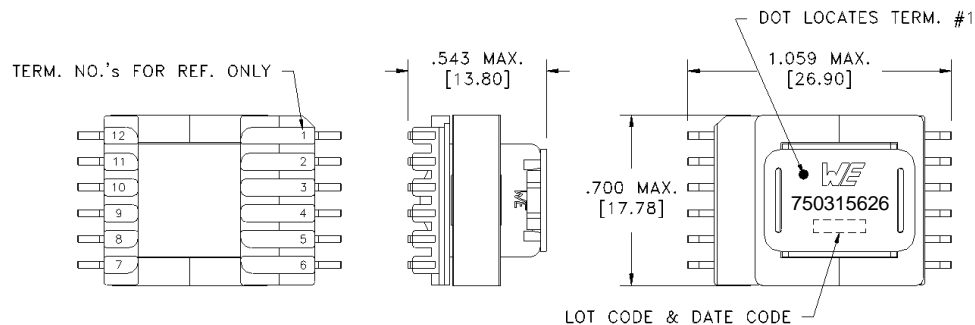


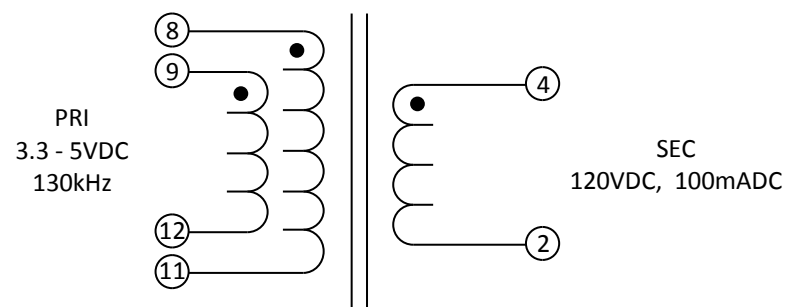
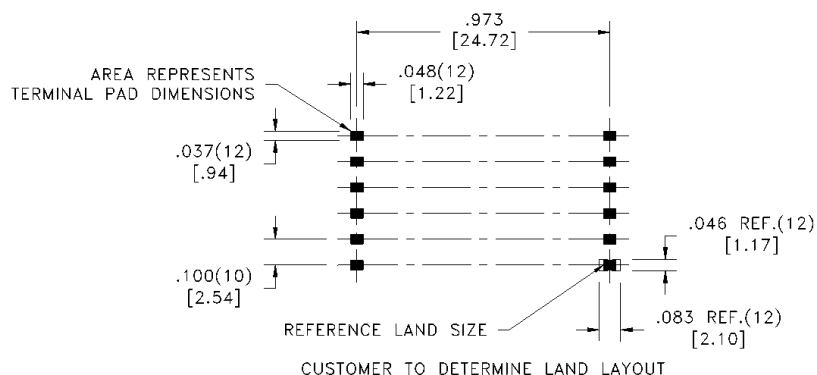
CUSTOMER TERMINAL	RoHS	LEAD(Pb)--FREE
Sn 96%, Ag 4%	Yes	Yes

more than you expect



ELECTRICAL SPECIFICATIONS @ 25° C unless otherwise noted:

PARAMETER	TEST CONDITIONS	VALUE	
D.C. RESISTANCE	8-12	tie(8+9,11+12), @20°C	0.008 ohms max.
D.C. RESISTANCE	4-2	@20°C	1.15 ohms ±10%
INDUCTANCE	8-12	tie(8+9,11+12), 100kHz, 100mV, Ls	1.50µH ±10%
SATURATION CURRENT	8-12	tie(8+9,11+12), 20% rolloff from initial	> 20A
LEAKAGE INDUCTANCE	8-12	tie(8+9,11+12,2+4), 100kHz, 100mV, Ls	100nH max.
DIELECTRIC	8-4	tie(8+9), 2500VAC, 1 second	2000VAC, 1 minute
URNS RATIO		(4-2):(8-12), tie(8+9,11+12)	15:1, ±2%



GENERAL SPECIFICATIONS:

OPERATING TEMPERATURE RANGE: -40°C to +125°C including temp rise.

Designed to comply with the following requirements as defined by IEC60950-1, EN60950-1, UL60950-1/CSA60950-1 and AS/NZS60950.1:

- Reinforced insulation for a primary circuit at a working voltage of 125Vpeak, Overvoltage Category II.

Application of the transformer allows for the leadwires between terminals 8&9 and 11&12 to solder bridge.
Customer to tie terminals 8&9 and 11&12 on PC board.

Wire insulation & RoHS status not affected by wire color. Wire insulation color may vary depending on availability.

DFM	SP	Packaging Specifications		Tolerances unless otherwise specified: Angles: ±1° Decimals: ±.005 [.13] Fractions: ±1/64 Footprint: ±.005 [.13]	DRAWING TITLE TRANSFORMER	PART NO. 750315626
DATE	6/23/2015	Method: Tape & Reel PKG-0799		This drawing is dual dimensioned. Dimensions in brackets are in millimeters.		
ENG	EJK					
REV.	00					
DATE	7/1/2015	www.we-online.com/midcom				SPECIFICATION SHEET 1 OF 1

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